

**Improved Die Package****ABSTRACT**

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A packaged die having a die pad, leads, and a power ring is disclosed. The die includes an electrical circuit thereon and is attached to the die pad. The leads are arranged around the die pad with at least one of the leads being connected to the die. The power ring includes a conductor disposed between the leads and the die pad, at least one power connection on the die being connected to the power ring. A layer of encapsulating material covers the die, die pad, the power ring, and the leads. The layer has a top surface, a bottom surface, and side surfaces. Each of the leads includes a conductor having a portion thereof exposed on the bottom surface. In addition, a portion of the conductor in the power ring is exposed on the bottom surface. In one embodiment, the exposed portions of the conductors include solder balls.

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